1000

Board Level Heat Sinks



ThermaFlo

P/N: 834000T00000 & 8340TRT00000

[1.00]



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Air Velocity - LFM

Heat Dissipated - Watts

600

800

400

200

PRODUCT SPECIFICATIONS

· Devices: D2 PAK, TO-263 • Size: 19.4 x 25.4 x 11.4 mm Material: Copper, 0.6 mm Thick

Type: Stamped

PCB Mounting: Surface Mount Technology

· Finish: Tin Plate

Package: Bulk or Tape & Reel

FEATURES & BENEFITS

- No Hardware Device Attachment
- Direct SMT Contact to PCB
- Solderable Legs
- RoHS Compliant



CUSTOMIZED HEATSINKS

- Specialized Body Configurations
- Contact Applications Engineering

Part Number	Packaging	Notes
834000T00000	Bulk	
8340TRT00000	Tape & Reel	Contact Factory for Tape and Reel Specs

100

60

40

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Temp Rise Above Ambient -

(Mounting Surface)

COMAIR ROTRON, INC